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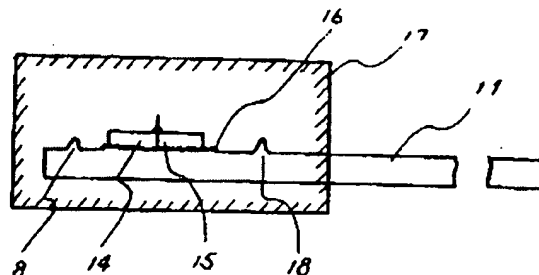
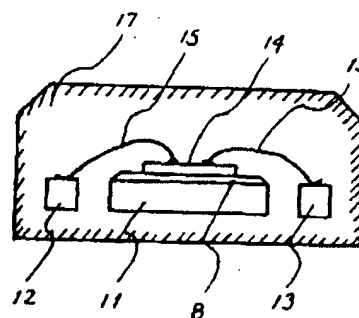
APPLICANT : NEC CORP;

INVENTOR : MINAMIGUCHI YOSHIYUKI;

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TITLE : SEMICONDUCTOR DEVICE

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ABSTRACT : **PURPOSE:** To prevent an improper bonding and a chip crack by forming lateral projections on the surface of leads, on which a semiconductor element is mounted, thereby preventing the mechanical pressure, and the deformation of leads due to the heat.

CONSTITUTION: Long projections 8, 18 are formed at both sides of a chip laterally of leads to a collector lead substrate 11. A semiconductor element 14 is mounted and soldered at a high temperature with metal solder 16 on the substrate 11. Then the element is bonded via fine metal wirings 15 to a base lead substrate 12 and an emitter lead substrate 13. This is sealed with resin 17, and the roots of the substrates 11, 12, 13 are cut.

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